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Vishay Semiconductors

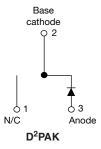
Ultrafast Rectifier, 15 A FRED Pt®

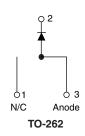




VS-ETL1506S-M3

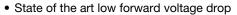
VS-ETL1506-1-M3



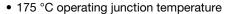


PRODUCT SUMMARY	
Package	TO-263AB (D ² PAK), TO-262AA
I _{F(AV)}	15 A
V _R	600 V
V _F at I _F	1.07 V
t _{rr} (typ.)	60 ns
T _J max.	175 °C
Diode variation	Single die

FEATURES







· Low leakage current

 Designed and qualified according to JEDEC®-JESD47



RoHS COMPLIANT HALOGEN

FREE

 Material categorization: for definitions of compliance please see www.vishav.com/doc?99912

DESCRIPTION/APPLICATIONS

State of the art, ultralow V_F, soft-switching ultrafast rectifiers optimized for Discontinuous (Critical) Mode (DCM) Power Factor Correction (PFC).

The minimized conduction loss, optimized stored charge and low recovery current minimized the switching losses and reduce over dissipation in the switching element and snubbers.

The device is also intended for use as a freewheeling diode in power supplies and other power switching applications.

APPLICATIONS

AC/DC SMPS 70 W to 400 W

e.g. laptop and printer AC adaptors, desktop PC, TV and monitor, games units, and DVD AC/DC power supplies.

ABSOLUTE MAXIMUM RATINGS							
PARAMETER	SYMBOL	TEST CONDITIONS	MAX.	UNITS			
Repetitive peak reverse voltage	V_{RRM}		600	V			
Average rectified forward current	I _{F(AV)}	T _C = 152 °C	15	^			
Non-repetitive peak surge current	I _{FSM}	T _C = 25 °C	200	A			
Operating junction and storage temperatures	T _J , T _{Stg}		-65 to +175	°C			

ELECTRICAL SPECIFICATIONS (T _J = 25 °C unless otherwise specified)						
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Breakdown voltage, blocking voltage	V_{BR}, V_{R}	$I_{R} = 100 \mu\text{A}$	600	-	-	
Economic voltage	V _F	I _F = 15 A	-	0.99	1.07	V
Forward voltage	VF	I _F = 15 A, T _J = 150 °C	-	0.85	0.91	
Deverage leakers as weent	_	$V_R = V_R$ rated	-	0.01	15	
Reverse leakage current	I _R	T _J = 150 °C, V _R = V _R rated	-	6	100	μA
Junction capacitance	C _T	V _R = 600 V	-	12	-	pF
Series inductance	L _S	Measured lead to lead 5 mm from package body	-	8.0	-	nH



DYNAMIC RECOVERY CHARACTERISTICS (T _J = 25 °C unless otherwise specified)							
PARAMETER	SYMBOL	TEST CO	MIN.	TYP.	MAX.	UNITS	
Reverse recovery time		$I_F = 1 \text{ A}, dI_F/dt = 100$	0 A/μs, V _R = 30 V	-	60	110	
		$I_F = 15 \text{ A}, dI_F/dt = 10$	$I_F = 15 \text{ A}, dI_F/dt = 100 \text{ A/}\mu\text{s}, V_R = 30 \text{ V}$		185	270	
	t _{rr}	T _J = 25 °C	I _F = 15 A dI _F /dt = 200 A/μs V _R = 390 V	-	210	-	ns -
		T _J = 125 °C		-	290	=	
Dook recovery ourrent		T _J = 25 °C		-	20	-	Α
Peak recovery current	I _{RRM}	T _J = 125 °C		-	26	-	_ ^
Develope management and a	0	T _J = 25 °C		-	2.2	=	
Reverse recovery charge	Q _{rr}	T _J = 125 °C		-	4.0	=	μC

THERMAL - MECHANICAL SPECIFICATIONS							
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS	
Maximum junction and storage temperature range	T _J , T _{Stg}		-65	-	175	°C	
Thermal resistance, junction to case	R _{thJC}		1	1.3	1.51	°C/W	
Thermal resistance, junction to ambient	R _{thJA}	Typical socket mount	-	-	70		
Thermal resistance, case to heatsink	R _{thCS}	Mounting surface, flat, smooth and greased	-	0.5	-		
Weight			ı	2.0	-	g	
vveignt			-	0.07	-	oz.	
Mounting torque			6 (5)	-	12 (10)	kgf · cm (lbf · in)	
Marking davisa		Case style D ² PAK modified		ETL1	ETL1506S		
Marking device		Case style TO-262		ETL1	506-1		

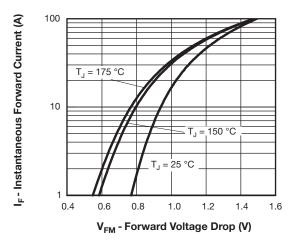


Fig. 1 - Typical Forward Voltage Drop Characteristics

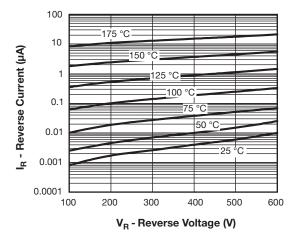


Fig. 2 - Typical Values of Reverse Current vs. Reverse Voltage

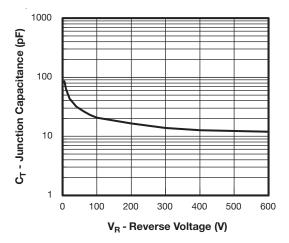


Fig. 3 - Typical Junction Capacitance vs. Reverse Voltage

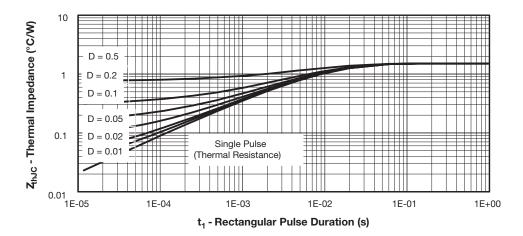


Fig. 4 - Max. Thermal Impedance Z_{thJC} Characteristics

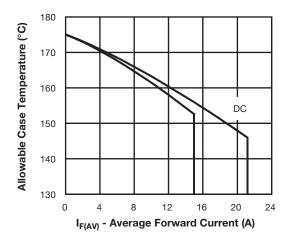


Fig. 5 - Maximum Allowable Case Temperature vs. Average Forward Current

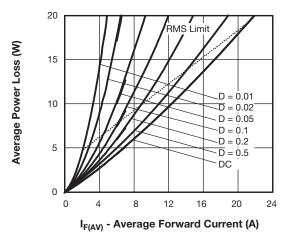


Fig. 6 - Forward Power Loss Characteristics

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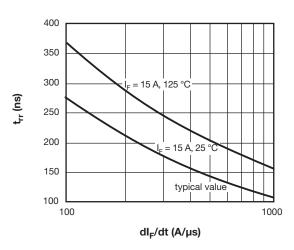


Fig. 7 - Typical Reverse Recovery Time vs. dl_F/dt

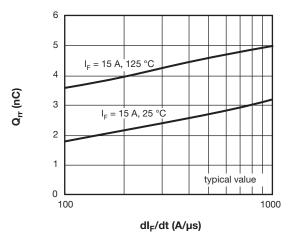


Fig. 8 - Typical Stored Charge vs. dl_F/dt

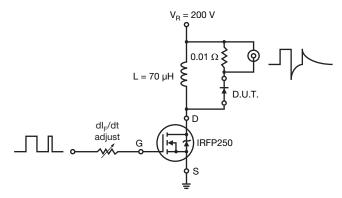
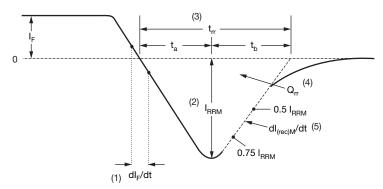


Fig. 9 - Reverse Recovery Parameter Test Circuit



- (1) dl_F/dt rate of change of current through zero crossing
- (2) I_{RRM} peak reverse recovery current
- (3) $\rm t_{rr}$ reverse recovery time measured from zero crossing point of negative going $\rm I_F$ to point where a line passing through 0.75 $\rm I_{RRM}$ and 0.50 $\rm I_{RRM}$ extrapolated to zero current.
- (4) $\mathbf{Q}_{\rm rr}$ area under curve defined by $\mathbf{t}_{\rm rr}$ and $\mathbf{I}_{\rm RRM}$

$$Q_{rr} = \frac{t_{rr} \times I_{RRM}}{2}$$

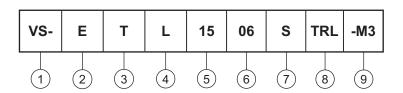
(5) dl_{(rec)M}/dt - peak rate of change of current during t_b portion of t_{rr}

Fig. 10 - Reverse Recovery Waveform and Definitions



ORDERING INFORMATION TABLE

Device code



1 - Vishay Semiconductors product

Circuit configuration
E = Single diode

3 - T = TO-220

L = Ultrafast recovery time

- Current code (15 = 15 A)

6 - Voltage code (06 = 600 V)

 $\overline{7}$ - \cdot S = D²PAK

- • -1 = TO-262

None = Tube (50 pieces)

TRL = Tape and reel (left oriented, for D²PAK package)

- • TRR = Tape and reel (right oriented, for D²PAK package)

9 - -M3 = Halogen-free, RoHS compliant, and terminations lead (Pb)-free

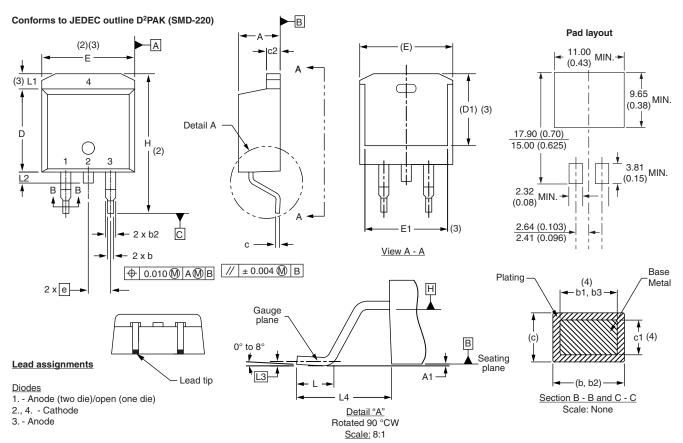
ORDERING INFORMATION (Example)						
PREFERRED P/N	QUANTITY PER TUBE	MINIMUM ORDER QUANTITY	PACKAGING DESCRIPTION			
VS-ETL1506S-M3	50	1000	Antistatic plastic tube			
VS-ETL1506-1-M3	50	1000	Antistatic plastic tube			
VS-ETL1506STRR-M3	800	800	13" diameter reel			
VS-ETL1506STRL-M3	800	800	13" diameter reel			

LINKS TO RELATED DOCUMENTS					
Dimensions	TO-263AB (D ² PAK)	www.vishay.com/doc?95046			
Dimensions	TO-262AA	www.vishay.com/doc?95419			
Part marking information	TO-263AB (D ² PAK)	www.vishay.com/doc?95444			
Fart marking imormation	TO-262AA	www.vishay.com/doc?95443			
Packaging information	TO-263AB (D ² PAK)	www.vishay.com/doc?95032			



D²PAK

DIMENSIONS in millimeters and inches



SYMBOL	MILLIN	IETERS	INC	HES	NOTES
STWIDOL	MIN.	MAX.	MIN.	MAX.	NOTES
Α	4.06	4.83	0.160	0.190	
A1	0.00	0.254	0.000	0.010	
b	0.51	0.99	0.020	0.039	
b1	0.51	0.89	0.020	0.035	4
b2	1.14	1.78	0.045	0.070	
b3	1.14	1.73	0.045	0.068	4
С	0.38	0.74	0.015	0.029	
c1	0.38	0.58	0.015	0.023	4
c2	1.14	1.65	0.045	0.065	
D	8.51	9.65	0.335	0.380	2

SYMBOL	MILLIM	ETERS	INC	HES	NOTES
STWBOL	MIN.	MAX.	MIN.	MAX.	NOTES
D1	6.86	8.00	0.270	0.315	3
E	9.65	10.67	0.380	0.420	2, 3
E1	7.90	8.80	0.311	0.346	3
е	2.54	2.54 BSC		0.100 BSC	
Н	14.61	15.88	0.575	0.625	
L	1.78	2.79	0.070	0.110	
L1	-	1.65	1	0.066	3
L2	1.27	1.78	0.050	0.070	
L3	0.25 BSC		0.010	BSC	
L4	4.78	5.28	0.188	0.208	

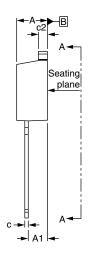
Notes

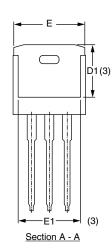
- $^{(1)}$ Dimensioning and tolerancing per ASME Y14.5 M-1994
- (2) Dimension D and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outmost extremes of the plastic body
- (3) Thermal pad contour optional within dimension E, L1, D1 and E1
- (4) Dimension b1 and c1 apply to base metal only
- (5) Datum A and B to be determined at datum plane H
- (6) Controlling dimension: inch
- (7) Outline conforms to JEDEC outline TO-263AB



TO-262

DIMENSIONS in millimeters and inches



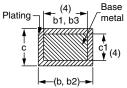


⊕ 0.010**⋒**|A**⋒**|B

Lead assignments



<u>Diodes</u>
1. - Anode (two die)/open (one die)
2., 4. - Cathode
3. - Anode



Section B - B and C - C Scale: None

CYMPOL	MILLIN	METERS	INC	HES	NOTES
SYMBOL	MIN.	MAX.	MIN.	MAX.	NOTES
А	4.06	4.83	0.160	0.190	
A1	2.03	3.02	0.080	0.119	
b	0.51	0.99	0.020	0.039	
b1	0.51	0.89	0.020	0.035	4
b2	1.14	1.78	0.045	0.070	
b3	1.14	1.73	0.045	0.068	4
С	0.38	0.74	0.015	0.029	
c1	0.38	0.58	0.015	0.023	4
c2	1.14	1.65	0.045	0.065	
D	8.51	9.65	0.335	0.380	2
D1	6.86	8.00	0.270	0.315	3
Е	9.65	10.67	0.380	0.420	2, 3
E1	7.90	8.80	0.311	0.346	3
е	2.54	BSC	0.100	BSC	
L	13.46	14.10	0.530	0.555	
L1	=	1.65	-	0.065	3
L2	3.56	3.71	0.140	0.146	

Notes

- (1) Dimensioning and tolerancing as per ASME Y14.5M-1994
- (2) Dimension D and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outmost extremes of the plastic body
- $^{(3)}$ Thermal pad contour optional within dimension E, L1, D1 and E1
- (4) Dimension b1 and c1 apply to base metal only
- (5) Controlling dimension: inches
- (6) Outline conform to JEDEC TO-262 except A1 (maximum), b (minimum) and D1 (minimum) where dimensions derived the actual package outline



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